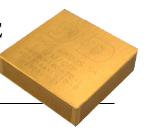


#### 3D PLUS - SYSTEM IN PACKAGE

# HOW TO BYPASS OBSOLESCENCE



## **General Description:**

3D Plus patented technology allows our customers to replace an obsolete component by a pin-to-pin compatible 3D Plus module.

This technology fits with a wide range of electronic devices such as ASICs, digital and analog hybrid, memories...

In order to ensure that the new module will identically match the original application, 3D plus covers a full scope of fields to explore.

## 1. Architecture and Technology study

Gathering of all information and documents describing and characterizing the original component such as datasheet, specifications, timing analysis...

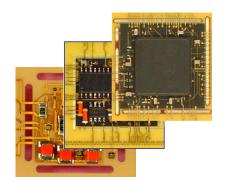


# Obsolete component

#### 2. Module Design and prototyping phase

3D Plus circuits design and prototyping including test development and implementation.

- •Schematic analysis
- Power analysis
- Mechanical analysis
- •Stacking study
- •Circuit breakdown & Flex schematic design
- •Flex layout
- •Module mechanical drawing
- •Design file
- •Test development
- •Test board design and manufacturing



#### 3. Manufacturing

3D Plus module fits exactly the obsolete component.

Same Functionality



Same Pin-out

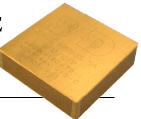
Same Footprint

Same Power Voltage

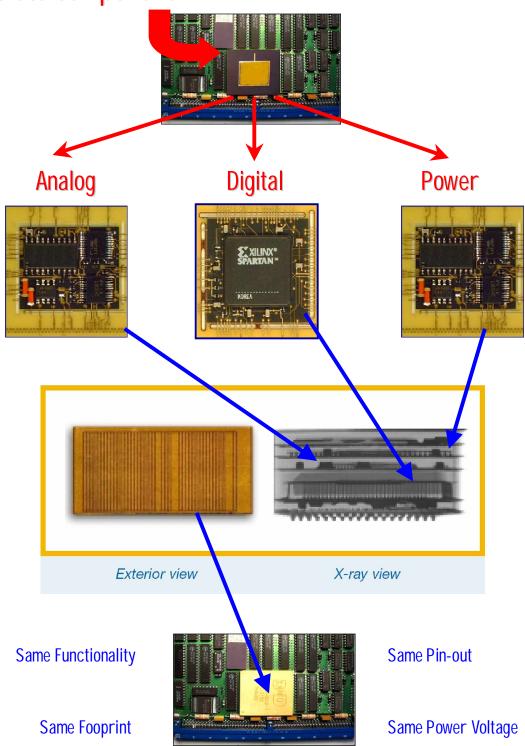


# 3D PLUS - SYSTEM IN PACKAGE

# HOW TO BYPASS OBSOLESCENCE



# Obsolete component



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